SN54HC365 THRU SN54HC368 SN74HC365 THRU SN74HC368 HEX BUS DRIVERS WITH 3-STATE OUTPUTS

SCLS139 D2684, DECEMBER 1982-REVISED JUNE 1989

- High-Current 3-State Outputs Drive Bus Lines, Buffer Memory Address Registers, or Up to 15 LSTTL Loads
- Choice of True or Inverting Outputs
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPe
- Dependable Texas Instruments Quality and Reliability

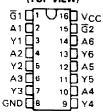
'HC365, HC367 'HC366, HC368 True Outputs
Inverting Outputs

description

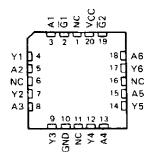
These Hex buffers and line drivers are designed specifically to improve both the performance and density of three-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The designer has a choice of selected combinations of inverting and noninverting outputs, symmetrical G (active-low control) inputs.

The SN54HC' family is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74HC' family is characterized for operation from -40°C to 85°C.

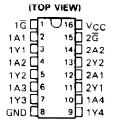
SN54HC365, SN54HC366 . . . J PACKAGE SN74HC365, SN74HC366 . . . D[†] OR N PACKAGE (TOP VIEW)



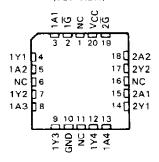
SN54HC365, SN54HC366 . . . FK PACKAGE (TOP VIEW)



SN54HC367, SN54HC368 . . . J PACKAGE SN74HC367, SN74HC368 . . . D † OR N PACKAGE



SN54HC367, SN54HC368...FK PACKAGE (TOP VIEW)

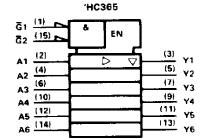


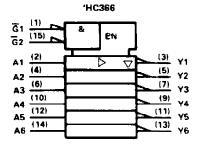
NC-No internal connection

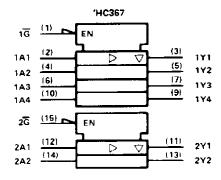
Texas Instruments

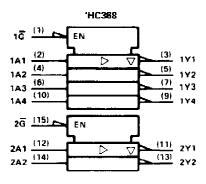
[†] Contact the factory for D availability.

logic symbols†

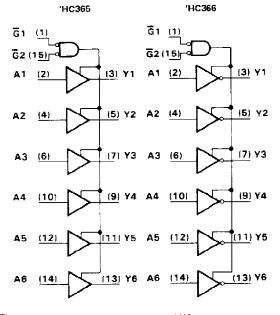








logic diagrams (positive logic)



HC368 **'HC367** 1**G** (1) 1G (1) (3) 1 Y 1(3) 1Y1 1A1 (2) 1A1(2) [5] 1Y2 1A2 (4) (5) 1Y2 1A2 (4) (7) 1Y3 1A3 (6) (7) 1Y3 1A3 (6) (9) 1Y4 1A4 (10) (9) 1Y4 1A4 (10) 2G (15) 2G (15) (<u>11)</u> 2Y1 2A1 (12) (11) 2Y1 2A1 (12) (13) 2Y2 2A2 (14) (13) 2Y2 2A2 (14)

Pin numbers shown are for D, J, and N packages.

[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range†

Supply voltage, VCC	0.5 V to 7 V
Input clamp current, IK (VI < 0 or VI > VCC)	± 20 mA
Output clamp current, IOK (VO < 0 or VO > VCC)	
Continuous output current, IQ (VQ = 0 to VCC)	
Continuous current through VCC or GND pins	
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package	
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package	
Storage temperature range65	

[†]Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN	SN54HC365 thru			74HC3	65	
							thru		
			SN54HC368			SN			
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage		voltage		5	6	2	5	6	>
		V _{CC} = 2 V	1.5			1.5			
۷ін	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			٧
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V	0		0.3	0		0.3	
VIL	Low-level input voltage	V _{CC} = 4.5 V	0		0.9	0		0.9	v
		Vcc = 6 V	0		1.2	0		1.2	
٧ı	Input voltage		0		Vcc	0		Vсс	>
۷o	Output voltage		0		V _{CC}	0		Vac	>
		V _{CC} = 2 V	0		1000	0		1000	
t _t Input transition (rise and fall)	input transition (rise and fall) times	V _{CC} = 4.5 V	0		500	0		500	ПS
		VCC = 6 V	0		400	0		400	
TΑ	Operating free-air temperature		- 55		125	-40		85	°C

SN54HC365 THRU SN54HC368 SN74HC365 THRU SN74HC368 HEX BUS DRIVERS WITH 3-STATE OUTPUTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	T _A = 2	SN54HC365 thru SN54HC368		SN74HC365 thru SN74HC368		UNIT	
			MIN TYP	MAX	MIN	MAX	MIN	MAX	
		2 V	1.9 1.998	3	1.9		1.9		
	$V_{I} = V_{IH} \text{ or } V_{IL}, I_{OH} = -20 \mu A$	4.5 V	4.4 4.499	•	4.4		4.4		
∨он		6 V	5.9 5.999)	5.9		5.9		٧
	V _I ≈ V _{IH} or V _{IL} , l _{OH} ≂ −6 mA	4.5 V	3.98 4.30)	3.7		3.84		
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -7.8$ mA	6 V	5.48 5.80)	5.2		5.34		
		2 V	0.002	0.1		0.1		0.1	
	V _I = V _{IH} or V _{IL} , I _{OL} = 20 μA	4.5 V	0.001	0.1		0.1		0.1	l
VOL	_	6 V	0.001	0.1		0.1		0.1	V
	VI ≈ VIH or VIL, IOL = 6 mA	4.5 V	0.17	0.26		0.4		0.33	
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 7.8$ mA	6 V	0.15	0.26		0.4		0.33	
l _l	V _I = VCC or 0	6 V	±0.1	± 100		± 1000		± 1000	nA
loz	Vo = Vcc or 0	6	± 0.01	±0.5		±10		± 5	μА
lcc .	V _I ≈ V _{CC} or 0, I _O = 0	6 V		8		160	_	80	μА
Ci		2 to 6 V	3	10	_	10		10	pF

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 50$ pF (see Note 1)

DADAMETER	FROM (INPUT)	TO (OUTPUT)	V	TA = 25	5°C	SN54HC'	SN74HC	
PARAMETER	FROM (INPUT)	10 (001201)	Vcc	MIN TYP	MAX	MIN MAX	MIN MAX	UNIT
. 1			2 V	50	95	145	120	
tpd	Α	Y	4.5 V	12	19	29	24	ns
, i			6 V	10	16	25	20	ļ
			2 V	100	190	285	238	
ten	₫	Y	4.5 V	26	38	57	48	ns
			6 V	21	32	48	41	
			2 V	50	175	265	240	
[†] dis	\overline{G}	Y	4.5 V	21	35	53	48	ns
			6 V	19	30	45	41	
			2 V	28	60	90	75	
tt		Any	4.5 ∨	8	12	18	15	ns
			6 V	6	10	15	13	

Cpd	Power dissipation capacitance per driver	No load, TA = 25°C	35 pF tγp

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 150 \text{ pF}$ (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		TA - 25	o^C	SN54H	3′	SN74	4HC'	
	PROM (MEDI)	10 (001701)	Vcc	MIN TYP	MAX	MIN M	AX	MIN	MAX	UNIT
			2 V	70	120		BO		150	
t _{pd}	Α	Y	4.5 V	17	24		36		30	ns
			6 V	14	20		31		25	
			2 V	140	230	:	345		285	
ten	G	· Y	4.5 V	30	46		69		57	ns
			6 V	28	39		59		48	
			2 V	45	210	3	315		265	
tt			4.5 V	17	42		63		53	ns
			6 V	13	36		53		45	

NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
5962-8682801EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8682801EA SNJ54HC366J
SN54HC366J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC366J
SN54HC366J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC366J
SNJ54HC366J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8682801EA SNJ54HC366J
SNJ54HC366J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8682801EA SNJ54HC366J

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

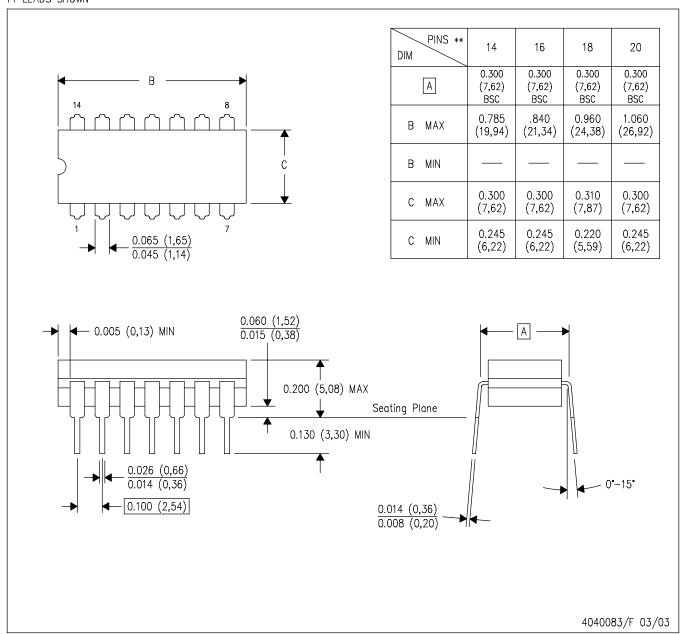


PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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